

ON Semiconductor®

### HUF76629D3ST-F085

# N-Channel Logic Level UltraFET® Power MOSFET **100V**, **20A**, **52m** $\Omega$

#### **Features**

- Typ  $r_{DS(on)}$  = 41m $\Omega$  at  $V_{GS}$  = 10V,  $I_D$  = 20A
- Typ  $Q_{g(tot)}$  = 39nC at  $V_{GS}$  = 10V,  $I_D$  = 20A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

### **Applications**

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Distributed Power Architectures and VRM
- Primary Switch for 12V Systems



(TO-252)

### MOSFET Maximum Ratings T<sub>.1</sub> = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
$V_{DSS}$	Drain to Source Voltage		100	V
$V_{GS}$	Gate to Source Voltage		±16	V
	Drain Current - Continuous (V <sub>GS</sub> =10) (Note 1) T <sub>C</sub> = 25°C		20	^
ID	Pulsed Drain Current	T <sub>C</sub> = 25°C	See Figure4	Α
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 2)	231	mJ
D	Power Dissipation		150	W
$P_D$	Derate above 25°C		1	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance Junction to Case		1	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient	(Note 3)	52	°C/W

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
HUF76629D3ST	HUF76629D3ST-F085	D-PAK(TO-252)	13"	12mm	2500 units

- 1: Current is limited by bondwire configuration.
- 2: Starting  $T_J = 25^{\circ}C$ , L = 1.8mH,  $I_{AS} = 16A$ ,  $V_{DD} = 100V$  during inductor charging and  $V_{DD} = 0V$  during time in avalanche 3:  $R_{\theta,JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder
- mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in<sup>2</sup> pad of 2oz copper.

Units

Max

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted

**Parameter** 

Off Characteristics							
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250μA, \	V <sub>GS</sub> = 0V	100	-	-	V
ı	Drain to Source Leakage Current	V <sub>DS</sub> =100V,	$T_{J} = 25^{\circ}C$	-	-	1	μА
IDSS		$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA
loco	Gate to Source Leakage Current	$V_{cc} = +16V$		_	_	+100	nΑ

**Test Conditions** 

Min

Тур

### **On Characteristics**

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		1.0	1.6	3.0	V
r <sub>DS(on)</sub>	Drain to Source On Resistance	I <sub>D</sub> = 20A,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	41	52	mΩ
		V <sub>GS</sub> = 10V	$T_J = 175^{\circ}C(Note 4)$	-	102	128	mΩ
		I <sub>D</sub> = 20A,	$T_J = 25^{\circ}C$		47	55	mΩ
		$V_{GS}$ = 4.5 $V$	$T_J = 175^{\circ}C(Note 4)$		115	135	mΩ

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		-	1280	-	pF
C <sub>oss</sub>	Output Capacitance			-	214	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			-	33	-	pF
$R_g$	Gate Resistance	f = 1MHz		-	2.5	-	Ω
$Q_{g(ToT)}$	Total Gate Charge	$V_{GS}$ = 0 to 10V	V <sub>DD</sub> = 50V	-	39	43	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$ $I_D = 20A$		-	2.3	3	nC
$Q_{gs}$	Gate to Source Gate Charge		-	-	3.5	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge			-	11	ı	nC

# **Switching Characteristics**

t <sub>on</sub>	Turn-On Time		-	-	27	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	7	-	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 50V, I <sub>D</sub> = 20A,	-	12	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10V, R_{GEN} = 8.2\Omega$	-	38	-	ns
t <sub>f</sub>	Fall Time		-	5	-	ns
t <sub>off</sub>	Turn-Off Time		-	-	47	ns

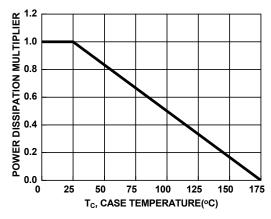
### **Drain-Source Diode Characteristics**

$V_{SD}$	ISOURCE TO DRAIN DIOGE VOITAGE	I <sub>SD</sub> = 20A, V <sub>GS</sub> = 0V	-	-	1.25	V
		$I_{SD} = 10A, V_{GS} = 0V$	-	-	1.0	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 20A, dI <sub>SD</sub> /dt = 100A/μs,	-	77	99	ns
Q <sub>rr</sub>	Reverse Recovery Charge	V <sub>DD</sub> =80V	-	221	305	nC

#### Notes:

4: The maximum value is specified by design at  $T_J$  = 175°C. Product is not tested to this condition in production.

### **Typical Characteristics**



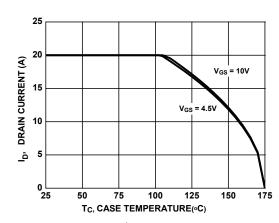


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

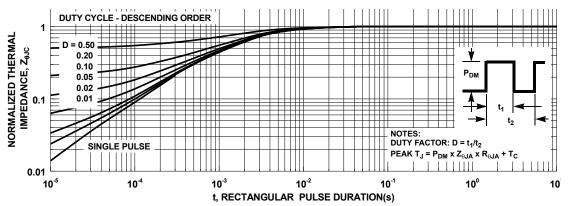


Figure 3. Normalized Maximum Transient Thermal Impedance

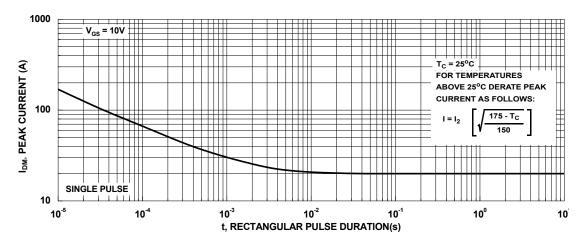
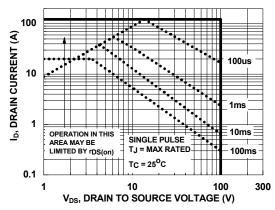


Figure 4. Peak Current Capability

### **Typical Characteristics**



100

(Y)

If R = 0

If R = 0

If R ≠ 0

If R ≠ 0

If R ≠ 0

If R = 0

If R ≠ 0

If R = 0

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If R ≠ 0

If R = 0

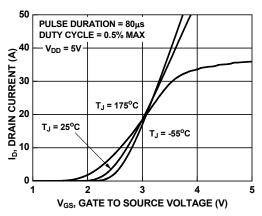
If R ≠ 0

If R

Figure 5. Forward Bias Safe Operating Area

NOTE: Refer to On Semiconductor Application Notes AN7514 and AN7515  $\,$ 

Figure 6. Unclamped Inductive Switching Capability



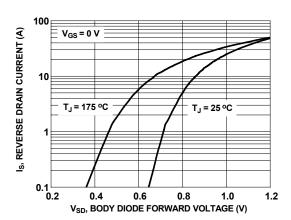
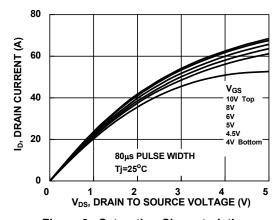


Figure 7. Transfer Characteristics

Figure 8. Forward Diode Characteristics



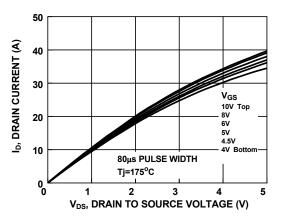


Figure 9. Saturation Characteristics

Figure 10. Saturation Characteristics

# **Typical Characteristics**

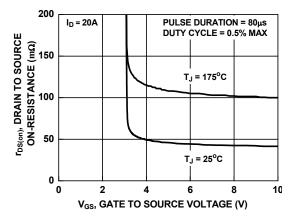


Figure 11. Rdson vs Gate Voltage

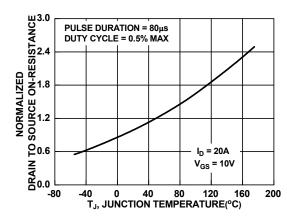


Figure 12. Normalized Rdson vs Junction Temperature

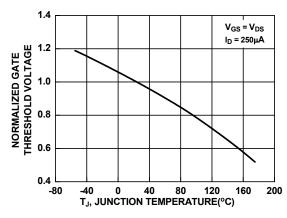


Figure 13. Normalized Gate Threshold Voltage vs
Temperature

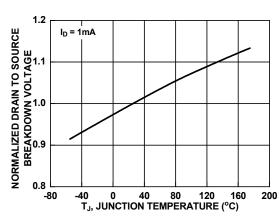


Figure 14. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

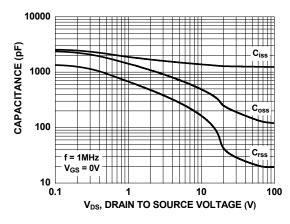


Figure 15. Capacitance vs Drain to Source Voltage

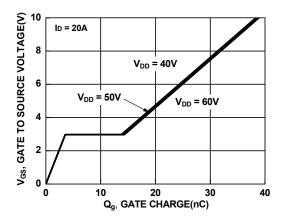


Figure 16. Gate Charge vs Gate to Source Voltage



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